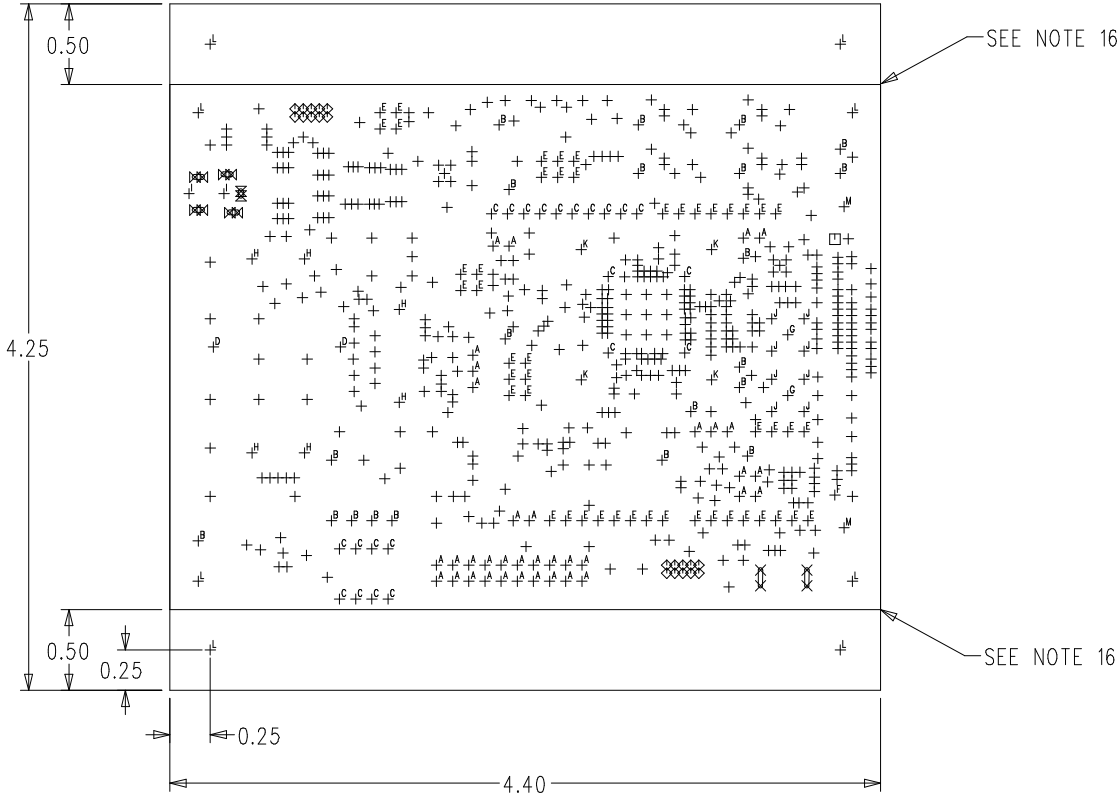
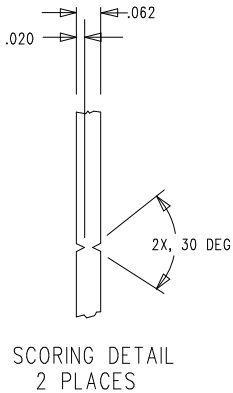
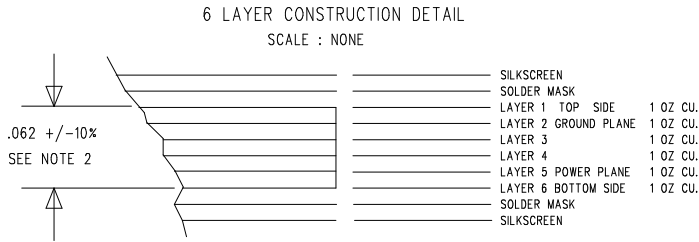


REVISIONS				
REV	DESCRIPTION OF CHANGE	DRFTR	DATE	APPROVED
0.1	NEW RELEASE	C.C.D.	08/05/14	
1.0	UPDATED PER ECO2015-014	C.C.D.	08/03/15	
1.1	UPDATED PER ECO2015-045	C.C.D.	11/19/15	
1.2	UPDATED PER ECO2016-001	C.C.D.	1/19/16	

SIZE	QTY	SYM	PLATED	TOL
0.012	524	+	YES	+/-0.003
0.028 x 0.126	2	✕	YES	+/-0.003
0.028	1	□	NO	+/-0.003
0.029	20	◇	YES	+/-0.003
0.032 x 0.06	1	⊠	YES	+/-0.003
0.032 x 0.078	4	⊠	YES	+/-0.003
0.038	36	+ ^A	YES	+/-0.003
0.04	21	+ ^B	YES	+/-0.005
0.041	22	+ ^C	YES	+/-0.003
0.042	2	+ ^D	YES	+/-0.003
0.043	48	+ ^E	YES	+/-0.003
0.044	1	+ ^F	NO	+/-0.005
0.047	2	+ ^G	YES	+/-0.003
0.053	6	+ ^H	NO	+/-0.003
0.063	2	+ ^I	NO	+/-0.003
0.067	8	+ ^J	YES	+/-0.003
0.09	4	+ ^K	YES	+/-0.003
0.125	8	+ ^L	NO	+/-0.005
0.144	2	+ ^M	NO	+/-0.005



- UNLESS OTHERWISE SPECIFIED
- BOARD TO BE FABRICATED PER IPC-6012B, CLASS 2.
 - MATERIAL: FR-370HR OR EQUIVALENT. OUTER LAYERS 1 OZ/SQFT CU INNER LAYERS 1 OZ/SQFT CU FINISHED .062 +/-10%. VENDOR MAY ADJUST THICKNESS TO FULFILL NOTE 9.
 - PLATING: ADDITIONAL CU PLATING 1 OZ/SQFT ALL HOLES PLATED THROUGH, EXCEPT AS NOTED IN HOLE LEGEND. MINIMUM PTH BARREL THICKNESS = 0.0008" MINIMUM AVERAGE PER IPC-6012B WITH AMENDMENT 1, CLASS 2 REQUIREMENTS. WITH NO SINGLE MEASUREMENT LESS THAN 0.00071 IN THE PLATED HOLES.
 - FINISH: SURFACES TO BE COATED BY ENIG OF 3 TO 5 MICROINCHES OVER A MINIMUM OF 150-200 MICROINCHES OF LOW STRESS NICKEL.
 - SOLDERMASK: SOLDER MASK TO BE TRANSPARENT GREEN LPI BOTH SIDES PER GERBER FILES. VENDOR MAY ADJUST SOLDERMASK PAD SIZE AS NEEDED.
 - SILKSCREEN: WHITE EPOXY INK, APPLY TO BOTH SIDES PER GERBER FILES.
 - ARTWORK: MINIMUM FEATURE SIZE = 0.005 MINIMUM AIR GAP = 0.004
 - ALL DIMENSIONS ARE IN INCHES.
 - CONTROLLED IMPEDANCE (+/-10%): ALL .007" TRACES TO BE 90 OHM DIFFERENTIAL PAIRS. ALL .005" TRACES TO BE 50 OHM SINGLE ENDED.
 - NON-FUNCTIONAL COPPER THIEVING IS ALLOWED ON OPEN AREAS.
 - VIAS SHOULD BE COVERED ACCORDING TO ONE OF THE FOLLOWING METHODS. METHOD 1 IS PREFERRED. METHOD 1: VIAS MUST BE FILLED WITH SOLDERMASK MATERIAL AFTER ELECTROLESS NICKEL/IMMERSION GOLD AND BEFORE PRIMARY LPI MASK. AFTER THE FILL IS CURED, THE PRIMARY MASK IS THEN APPLIED WITH NO VIA APERTURES BOTH SIDES. METHOD 2: AFTER APPLICATION OF FULL BODY ELECTROLESS NICKEL/IMMERSION GOLD, APPLY PRIMARY MASK WITH REDUCED VIA APERTURES THAT ARE 6 MILS LARGER THAN DRILLED HOLE DIAMETER BOTH SIDES. THEN APPLY SOLDER MASK PLUG ON COMPONENT SIDE.
 - VIA HOLES (.012) REQUIRE TANGENCY ONLY, INSTEAD OF ANNULAR RING.
 - TEARDROP PADS ARE ACCEPTABLE WHERE NEEDED.
 - REMOVAL OF NON-FUNCTIONAL PADS ON LAYERS 3 AND 4 IS ACCEPTABLE.
 - USE IPC-D-356A NETLIST AS SUPPLIED FOR CHECKING.
 - V SCORE 1 LINE ON BOTH SIDES OF THE BOARD. SEE DETAIL.
 - BUILD AS 1-UP PCB.



UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN INCHES TOLERANCES ARE : .xx +/- .010 .xxx +/- .005	CONTRACT NO.		2 Elizabeth Drive Chelmsford, MA 01824	
	APPROVALS	DATE		
MATERIAL SEE NOTES	DRAWN CHECKED	C.C.D. 1/19/16	FABRICATION DRAWING ADUCM3029 EZ-KIT	
FINISH SEE NOTES	ENGINEERING QUALITY			
DO NOT SCALE THIS DRAWING	MANUFACTURING		SIZE B	DWG. NO. A0637-2014
			SCALE 1 : 1	SHEET 1 OF 1